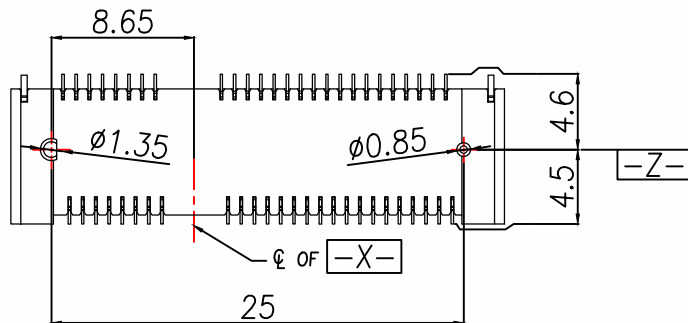
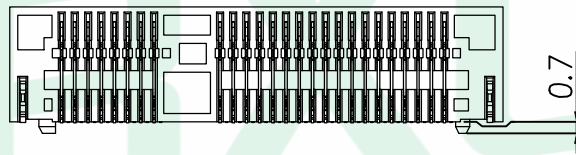
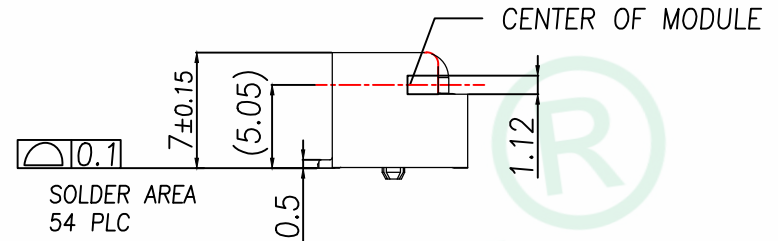
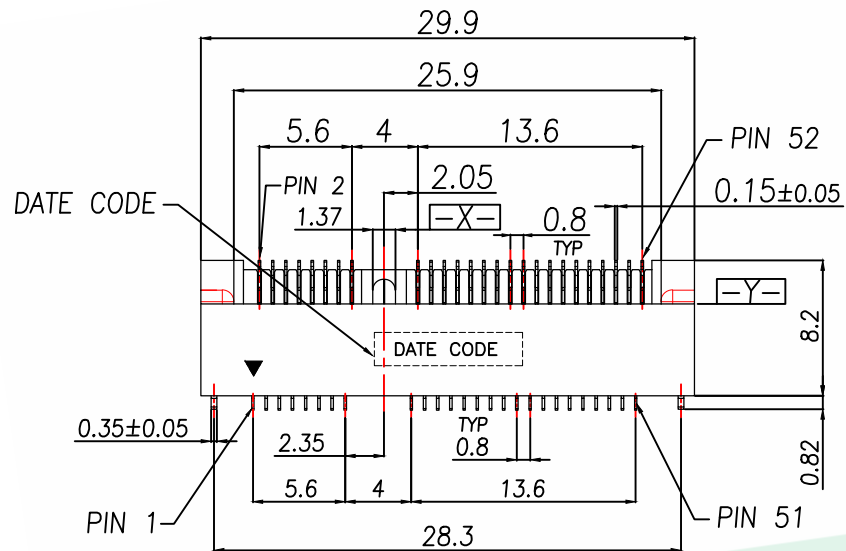




SCALE 0.6

REV.	DESCRIPTION	ECN NO.	NAME	DATE



NOTES:

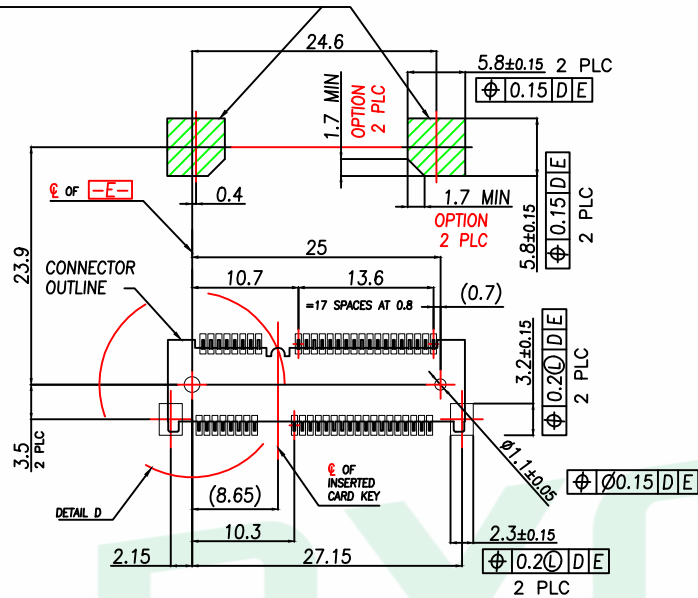
- MATERIAL:
HOUSING: THERMOPLASTIC, HIGH TEMP, UL94V-0, BLACK COLOR,
CONTACTS: COPPER ALLOY.
PEGS: COPPER ALLOY.
- FINISH:
CONTACTS: SELECTED GOLD PLATING ON THE CONTACT AREA,
1u" MIN. GOLD PLATING ON THE SOLDER TAILS,
50 u" MIN. NICKEL UNDERPLATING OVER ALL.
PEGS: 120u" MIN. MATTE-TIN OVER 50u" MIN. NICKEL.

GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD			 
DIM.	TOL.	TITLE: 0.80MM PITCH MINPCIEXPRESS HIGH=7.0mm 52 PIN CONNECTOR			
x	±0.40	DWG. NO.: PCIE-H7.0-P5236		CHECKED: MAX	
x.x	±0.30	PART NO.: PCIE-H7.0-P5236		DRAWN: ELLA	
x.xx	±0.20	UNIT: mm		APPROVED: WILL	
GENERAL ANGLE:		SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn
x.	±1.5°				
x.x'	±1.0°				
x.xx'	±0.5°				

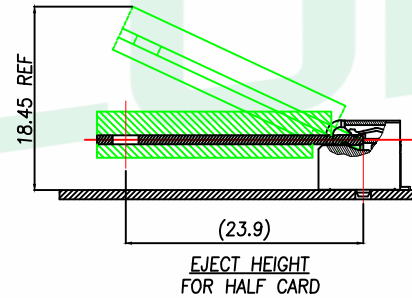
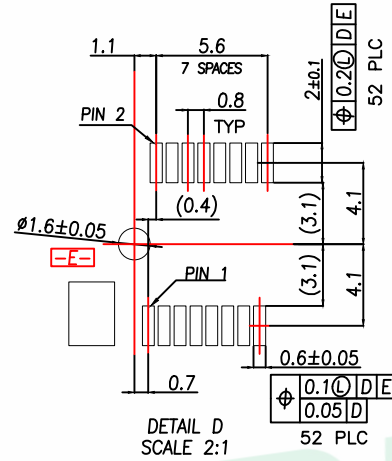
SCALE 0.6

REV.	DESCRIPTION	ECN NO.	NAME	DATE

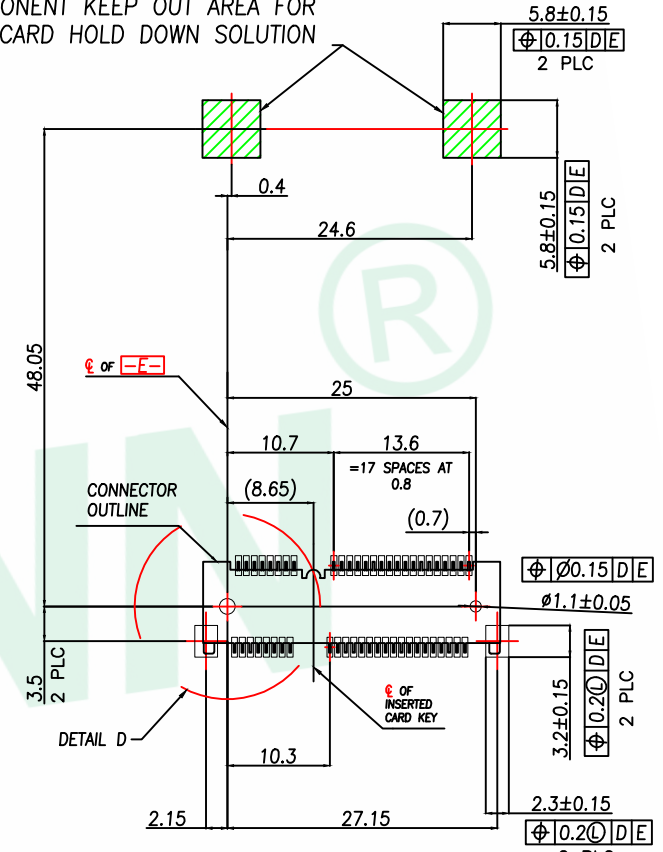
COMPONENT KEEP OUT AREA FOR
CARD HOLD DOWN SOLUTION



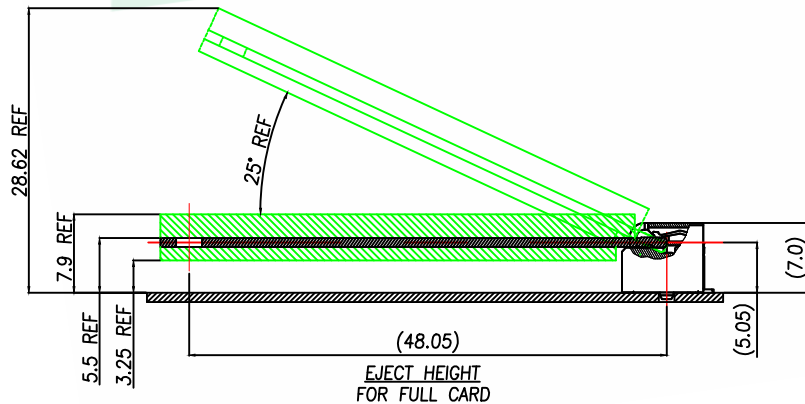
-D- IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)





COMPONENT KEEP OUT AREA FOR
CARD HOLD DOWN SOLUTION



-D- IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR FULL CARD CONNECTOR
(TOP VIEW)



GENERAL TOLERANCE		DONGGUAN BAOXUN PRECISION TECHNOLOGY CO., LTD			 
DIM. TOL.		TITLE: 0.80MM PITCH MINPCIEXPRESS HIGH=7.0mm 52 PIN CONNECTOR			
x. ±0.40		DWG. NO.: PCIE-H7.0-P5236		CHECKED: MAX	
x.x ±0.30		PART NO.: PCIE-H7.0-P5236		DRAWN: ELLA	
x.xx ±0.20		UNIT: mm		APPROVED: WILL	
GENERAL ANGLE:		SCALE: none	SHEET: 1 of 1	DWG. SIZE: A4	LAYER: bxconn
x. ±1.5°					
x.x ±1.0°					
x.xx ±0.5°					

